

Amendments to the Specification:

In the title:

Please change the title to read as follows:

"REDUCED-SIZE MULTI-CHIP MODULE WITH HIGH-SPEED SIGNAL
EXCHANGE"

Please replace the paragraph beginning on page 6,
line 2 with the following amended paragraph:

The semiconductor chips SH, SDRAM and ASIC shown in
FIG. 2 are mounted on one main surface of the mounting board
in such a manner that the ~~circuit-formed~~ circuit-formed
surfaces of the semiconductor chips are in opposed relation
to ~~each other~~ the mounting board. A plurality of external
terminals of the multi-chip module are arranged on the other
main surface of the mounting board. This configuration makes
possible a compact multi-chip module regardless of the area
occupied by the plurality of the semiconductor chips and the
area required for arranging the plurality of the external
terminals.

Please replace the paragraph beginning on page 15,
line 25 with the following amended paragraph:

As shown in FIG. 10, the MCM according to this embodiment has a basically similar configuration to the MCM described with reference to FIGS. 1 to 8 above except for the difference described below. Specifically, the Au stud bumps 1 are each electrically and mechanically connected to the connector 4 of the mounting board 3 through a coupling member 2. Between the semiconductor chip 5 and the mounting board 3, an underfill resin 6 is filled to suppress the damage to the semiconductor chip 5 which otherwise might be caused by the concentration of thermal stress due to the difference in the coefficient of thermal expansion between the mounting board 3 and the semiconductor chip 5. Further, the reverse side of the mounting board 3 is formed with land electrodes 7 as external terminals for electrically connecting a printed wiring board (PCB), for example.